



| Parameter | Rating | Units |
|-----------------------|----------|----------------------------------|
| AC Operating Voltage | 20 - 240 | V_{rms} |
| Load Current | 3 | A _{rms} |
| On-State Voltage Drop | 0.8 | V_{rms} (at $I_L = 3A_{rms}$) |
| Blocking Voltage | 600 | V_P |

Features

- Load Current up to 3A_{rms}
- 600V_P Blocking Voltage
- 5mA Sensitivity
- · Zero-Crossing Detection
- DC Control, AC Output
- Optically Isolated
- Low EMI and RFI Generation
- High Noise Immunity
- Flammability Rating UL 94 V-0

Applications

- Programmable Control
- Process Control
- Power Control Panels
- Remote Switching
- Gas Pump Electronics
- Contactors
- Large Relays
- Solenoids
- Motors
- Heaters

Description

CPC1966Y is an AC Solid State Switch utilizing dual power SCR outputs. This device also includes zero-cross turn-on circuitry, and is specified with a blocking voltage of $600V_{\rm p}$.

In addition, the tightly controlled zero-cross circuitry ensures low noise switching of AC loads by minimizing the generation of transients.

The optically coupled input and output circuits provide $3750V_{rms}$ of isolation and noise immunity between the control and load circuits. As a result, the CPC1966Y is well suited for industrial environments where electromagnetic interference would disrupt the operation of plant facility communication and control systems.

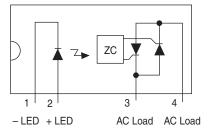
Approvals

- UL Recognized Component: File E69938
- CSA Certified Component: File 1172007

Ordering Information

| Part # | Description |
|----------|---|
| CPC1966Y | 4-Pin (8-Pin Body) Power SIP Package(25/Tube) |

Pin Configuration











Absolute Maximum Ratings @ 25°C

| Parameter | Ratings | Units |
|--------------------------------------|-------------|------------------|
| Blocking Voltage (V _{DRM}) | 600 | V_{P} |
| Reverse Input Voltage | 5 | V |
| Input Control Current | 50 | mA |
| Peak (10ms) | 1 | Α |
| Input Power Dissipation ¹ | 150 | mW |
| Total Power Dissipation ² | 2400 | mW |
| Isolation Voltage, Input to Output | 3750 | V _{rms} |
| Operational Temperature, Ambient | -40 to +85 | °C |
| Storage Temperature | -40 to +125 | °C |

 $^{^{1}}$ Derate linearly 1.33 mW / $^{\circ}\text{C}$

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

Electrical Characteristics @ 25°C

| Parameters | Conditions | Symbol | Min | Тур | Max | Units |
|--|---|-------------------|------|------|-----|------------------|
| Output Characteristics | • | | | | | |
| Blocking Voltage | I _L =1μA | V_{DRM} | 600 | - | - | V |
| Load Current | Free Air, V _L =120-240V _{rms} | | | | | |
| Continuous | | I _L | 0.1 | - | 3 | A _{rms} |
| Surge | t <u><</u> 16ms | I _P | - | - | 30 | A |
| Off State Leakage Current | V _{DRM} | I _{LEAK} | - | - | 100 | μA _P |
| On-State Voltage Drop ¹ | I _L =2A _P | - | - | 0.88 | 1.1 | V _P |
| Off-State dV/dt | - | dV/dt | 500 | - | - | V/µs |
| Switching Speeds | | | | | | |
| Turn-on | $I_F = 5 \text{ mA}$ | t _{on} | - | - | 0.5 | cycles |
| Turn-off | · | t _{off} | - | - | 0.5 | cycles |
| Zero-Cross Turn-On Voltage ² | 1st half-cycle | - | - | 5 | 20 | V |
| | Subsequent half-cycle | - | - | - | 5 | V |
| Holding Current | - | I _H | - | 44 | 50 | mA |
| Latching Current | - | IL | - | 48 | 75 | mA |
| Operating Frequency | - | | 20 | - | 500 | Hz |
| Load Power Factor for Guaranteed Turn-On ³ | 60Hz | PF | 0.25 | - | - | - |
| Input Characteristics | | 1 | | | l l | |
| Input Control Current to Activate 4 | 60Hz | I _F | - | - | 5 | mA |
| Input Drop-out Voltage | - | - | 0.8 | - | - | V |
| Input Voltage Drop | I _F =5mA | V _F | 0.9 | 1.36 | 1.5 | V |
| Reverse Input Current | V _B =5V | I _R | - | - | 10 | μΑ |
| Common Characteristics | | | | | | |
| Input to Output Capacitance | V _{IO} =0V, f=1MHz | C _{IO} | - | - | 3 | pF |

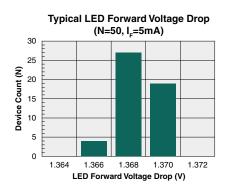
¹ Tested at a peak value equivalent.

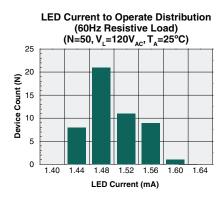
² Derate output power linearly 20 mW / °C

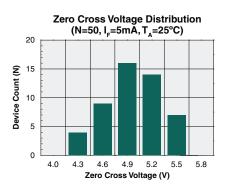
² Zero Cross 1st half-cycle @ <100Hz. ³ Snubber circuits may be required at low power factors. ⁴ For high-noise environments, or for high-frequency operation, use $I_F \ge 10$ mA.

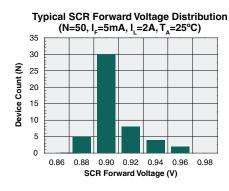


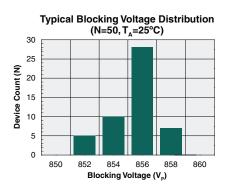
PERFORMANCE DATA*

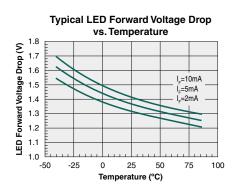


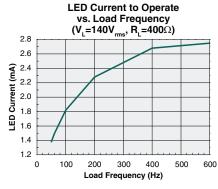


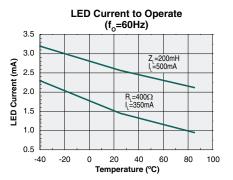








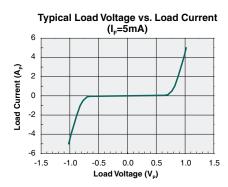


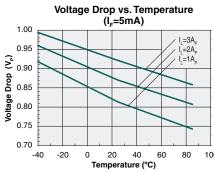


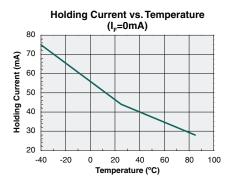
*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.

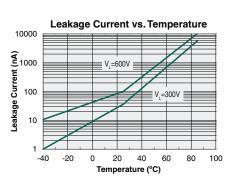


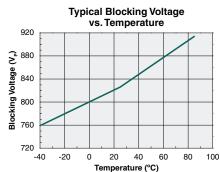
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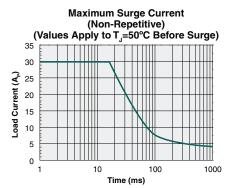














Manufacturing Information

ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

Soldering Profile

The Maximum Solder Temperature and the Maximum Total Dwell Time in all solder waves the device pins (leads) may be at the Maximum Solder Temperature is given in the table below. The body temperature of the device must not exceed the Maximum Body Temperature shown below at any time during the soldering process.

| Device | Maximum Solder Temperature | Maximum Body Temperature | Maximum Total Dwell Time | Wave Cycles |
|----------|----------------------------|--------------------------|--------------------------|-------------|
| CPC1966Y | 260°C | 245°C | 10 seconds | 1 |

Board Wash

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to halide flux or solvents.



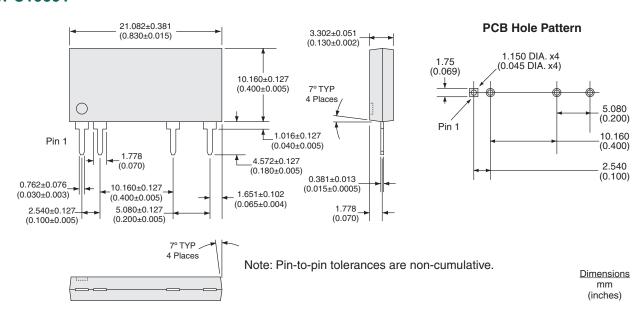






MECHANICAL DIMENSIONS

CPC1966Y



For additional information please visit our website at: https://www.ixysic.com

